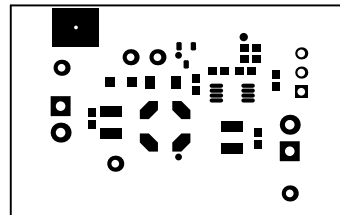
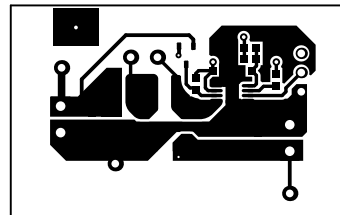


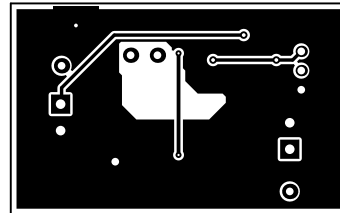
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP30296	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: .TID		
PLOT NAME = Top Overlay	GENERATED : 8/21/2017 10:46:26	TEXAS INSTRUMENTS	



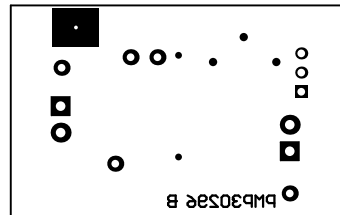
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP30296	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: .TID		
PLOT NAME = Top Solder Mask	GENERATED : 8/21/2017 10:46:27	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP30296	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: .TID		
PLOT NAME = Top Layer	GENERATED : 8/21/2017 10:46:28	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP30296	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: .TID		
PLOT NAME = Bottom Layer	GENERATED : 8/21/2017 10:46:29	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP30296	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: .TID		
PLOT NAME = Bottom Solder Mask	GENERATED : 8/21/2017 10:46:30	TEXAS INSTRUMENTS	

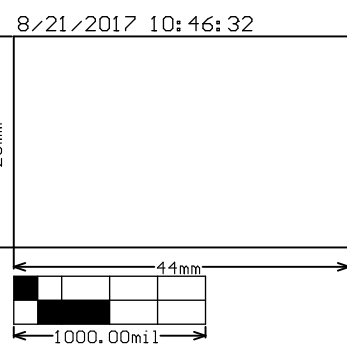


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP30296	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: .TID		
PLOT NAME = Bottom Overlay	GENERATED : 8/21/2017 10:46:31		TEXAS INSTRUMENTS

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
▽	2	11.81mil (0.300mm)	PTH	Round	Top Layer - Bottom Layer	
☆	4	19.69mil (0.500mm)	PTH	Round	Top Layer - Bottom Layer	
□	8	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
○	4	50.00mil (1.270mm)	PTH	Round	Top Layer - Bottom Layer	
	18 Total					



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP30296	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: .TID		
PLOT NAME = Drill Drawing	GENERATED : 8/21/2017 10:46:31	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP30296	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: .TID		
PLOT NAME = Board Dimensions	GENERATED : 8/21/2017 10:46:32	TEXAS INSTRUMENTS	

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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